

Principles of Micro- and Nanofabrication for Electronic and Photonic Devices

Film Deposition Part VI: Wet Process

Xing Sheng 盛兴

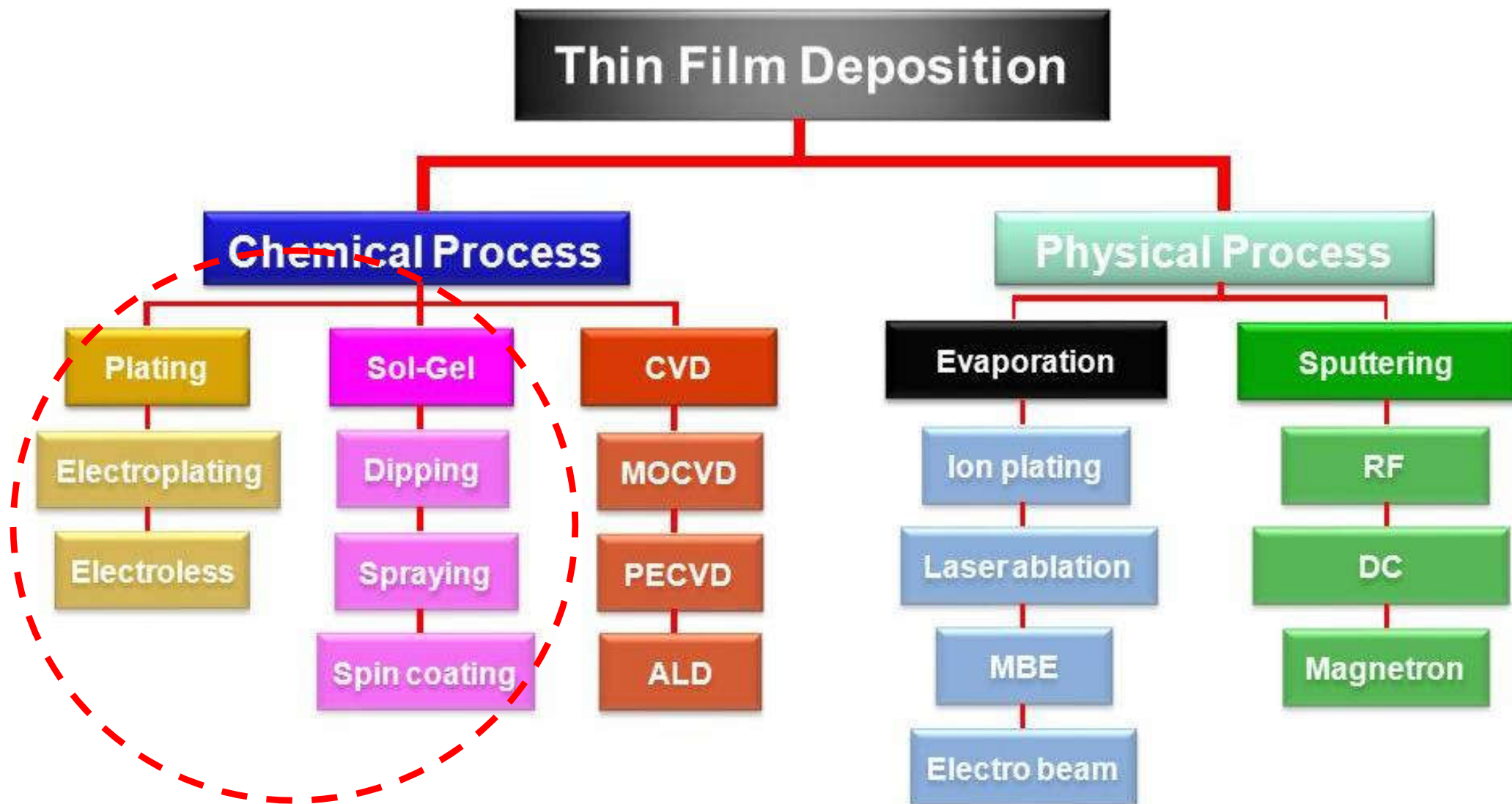


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Film Deposition

Thin Film Deposition



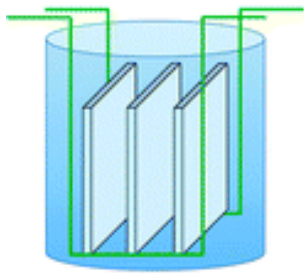
PVD: Physical Vapor Deposition

CVD: Chemical Vapor Deposition

→ 'dry' process

Solution based Deposition

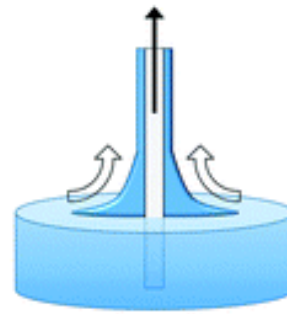
'wet' process



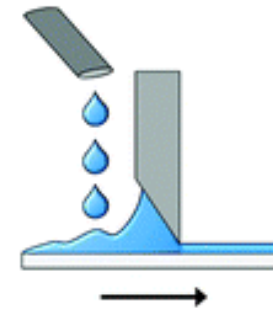
Chemical Bath



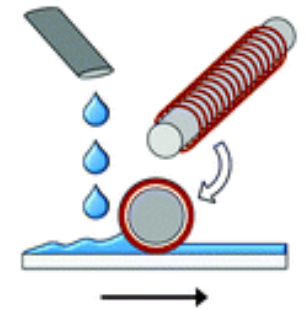
Spin-coating



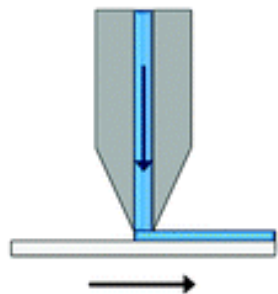
Dip-coating



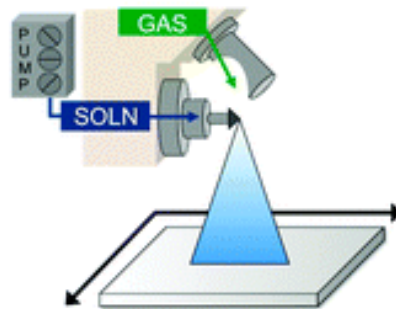
Doctor Blade



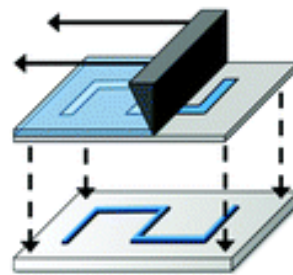
Metering Rod



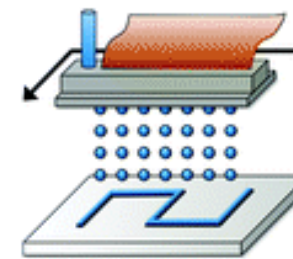
Slot-casting



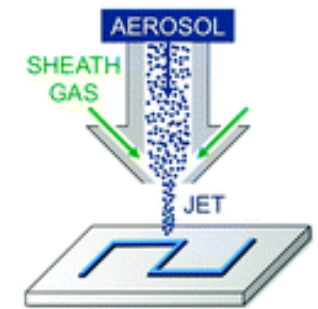
Spray-coating



Screen Printing



Inkjet Printing



Aerosol Jet

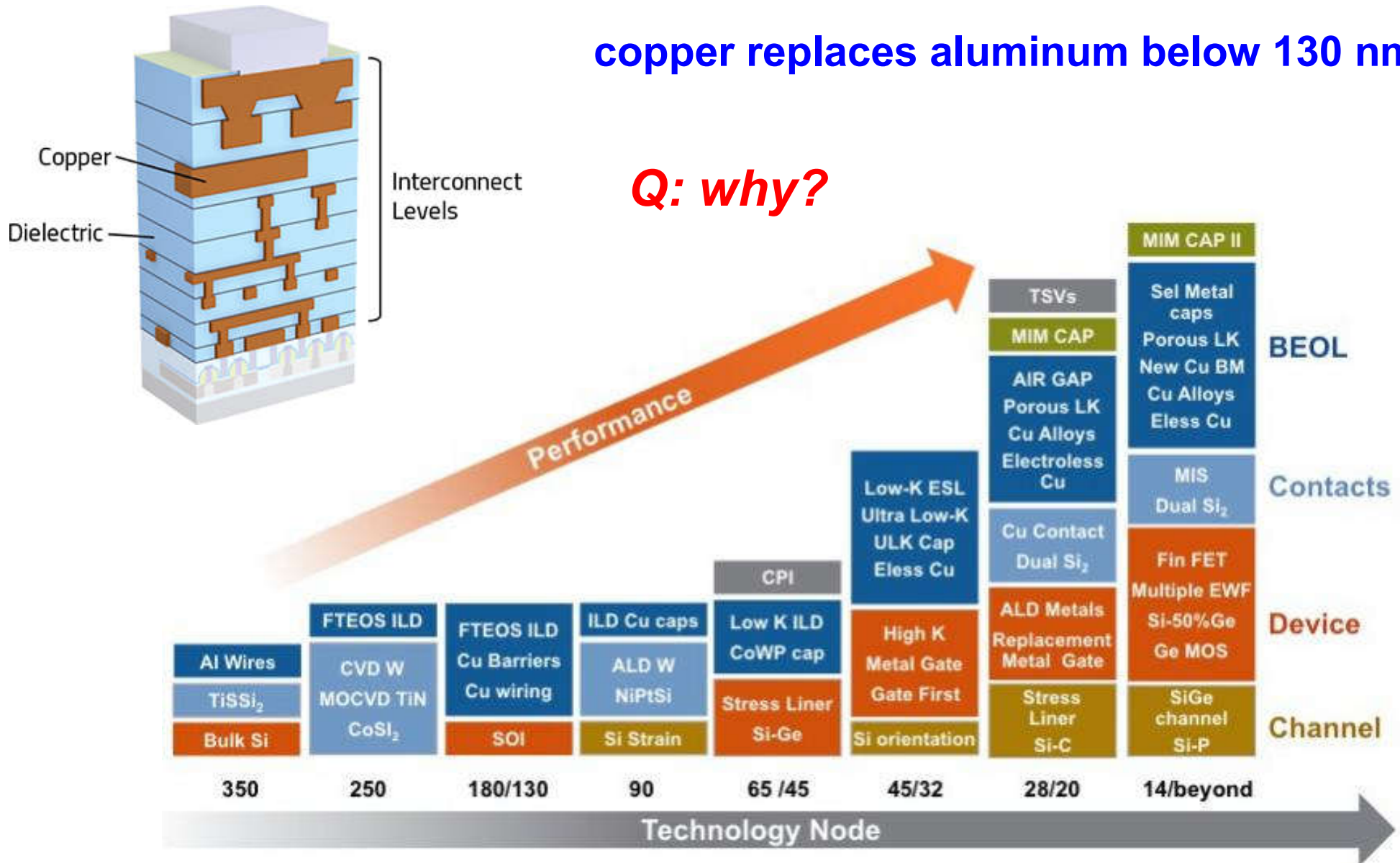
Examples

- **Copper - electroplating**
- **Silver - electroless plating**
- **Liquid Phase Epitaxy (LPE)**
- **Spin-on glass**
- **Organics / Quantum Dots**

Interconnects for CMOS

copper replaces aluminum below 130 nm

Q: why?



Interconnects for CMOS

Aluminum

- **conductive**
- **reliable and stable**
- **easy deposition**
- **easy etching**
- **low diffusivity in Si and SiO₂**
- **good adhesion with Si and SiO₂**
- **low cost**
- **...**

Interconnects for CMOS

Aluminum

- conductive
- reliable and stable
- easy deposition
- easy etching
- low diffusivity in Si and SiO₂
- good adhesion with Si and SiO₂
- low cost
- ...

Copper

- more conductive

VS.

Copper wins!

Interconnects for CMOS

Reduces RC circuit delay, reduce power consumption

$$t \sim RC$$

$$P \sim I^2 R$$

below 130 nm →

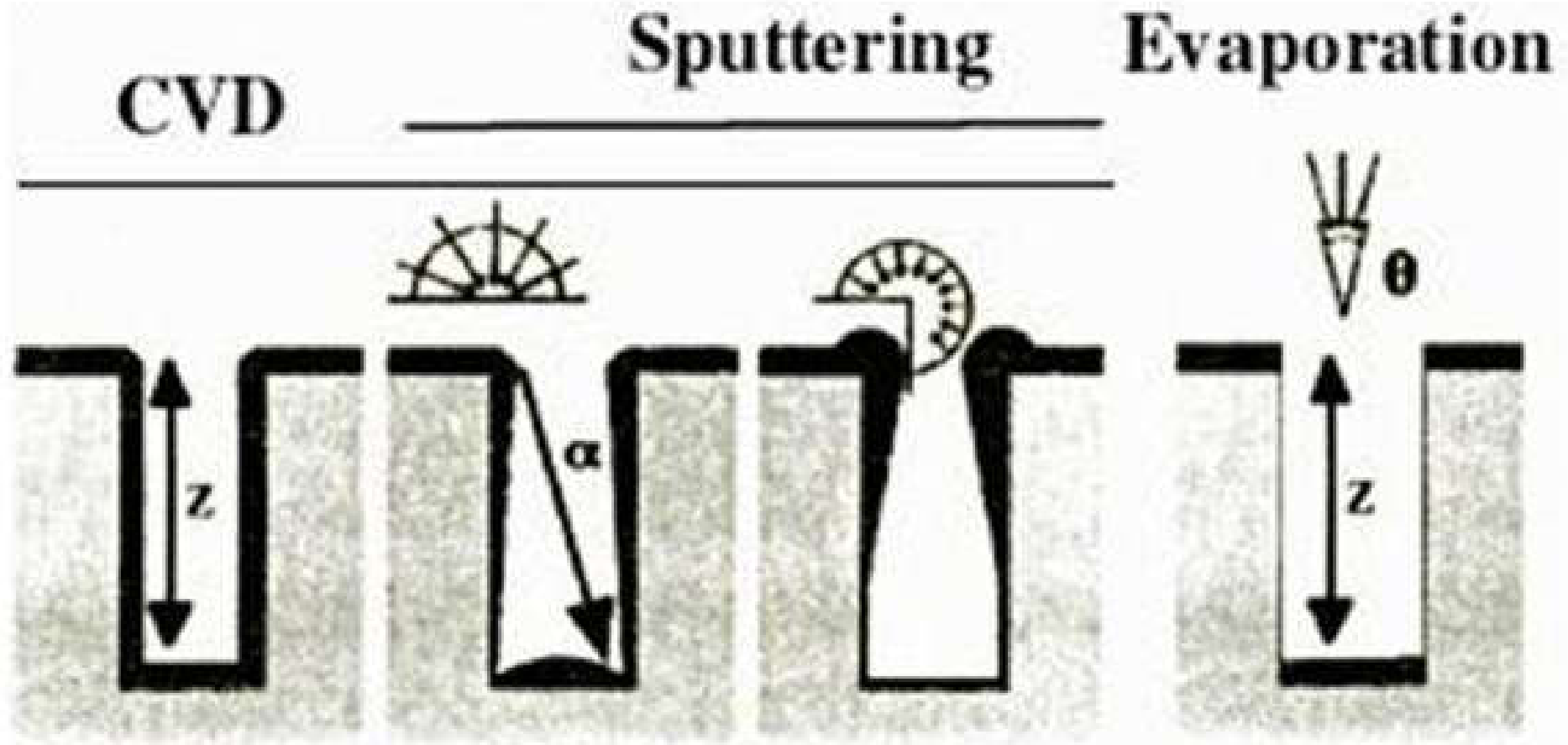
above 130 nm →

Materials	Conductivity (10^6 S/m)
Graphene (C)	100
Silver (Ag)	63
Copper (Cu)	60
Gold (Au)	43
Aluminum (Al)	38

- Al is cheap and easy to deposit
- Ag and Au are expensive
- Cu is cheap and conductive
- Carbon (graphene) is the best

what is next, Ag or Carbon?

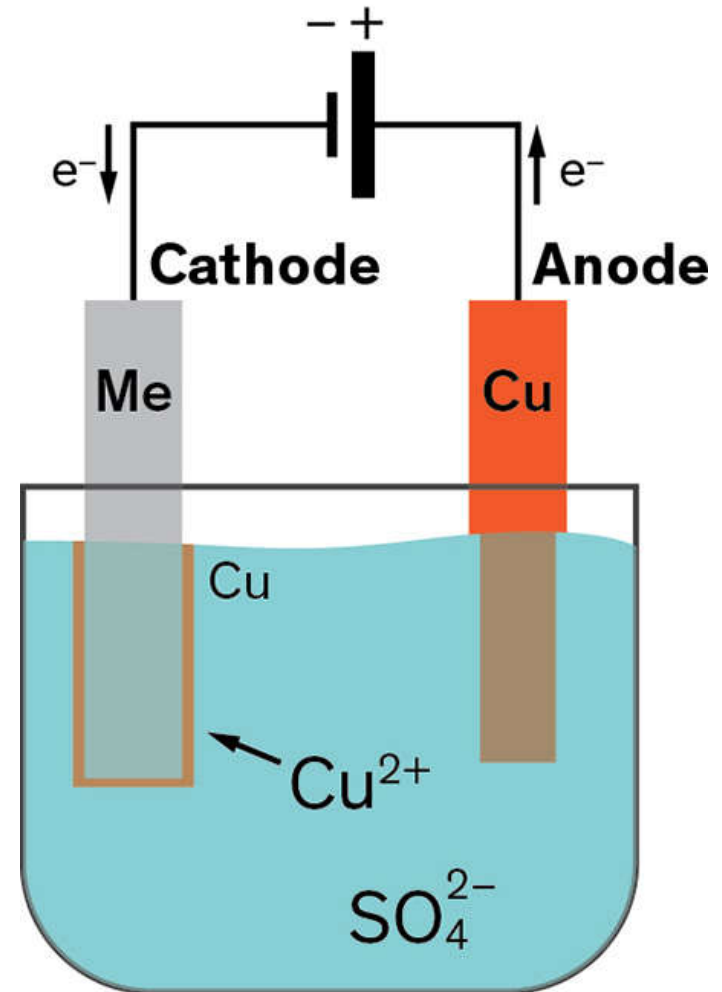
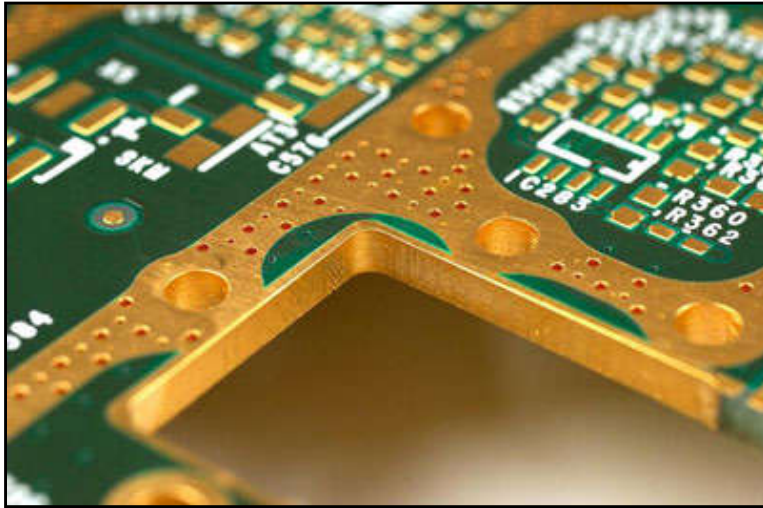
Step Coverage



***CVD is preferred for via filling
Al, W can be deposited by CVD
but CVD Cu is very difficult ...***

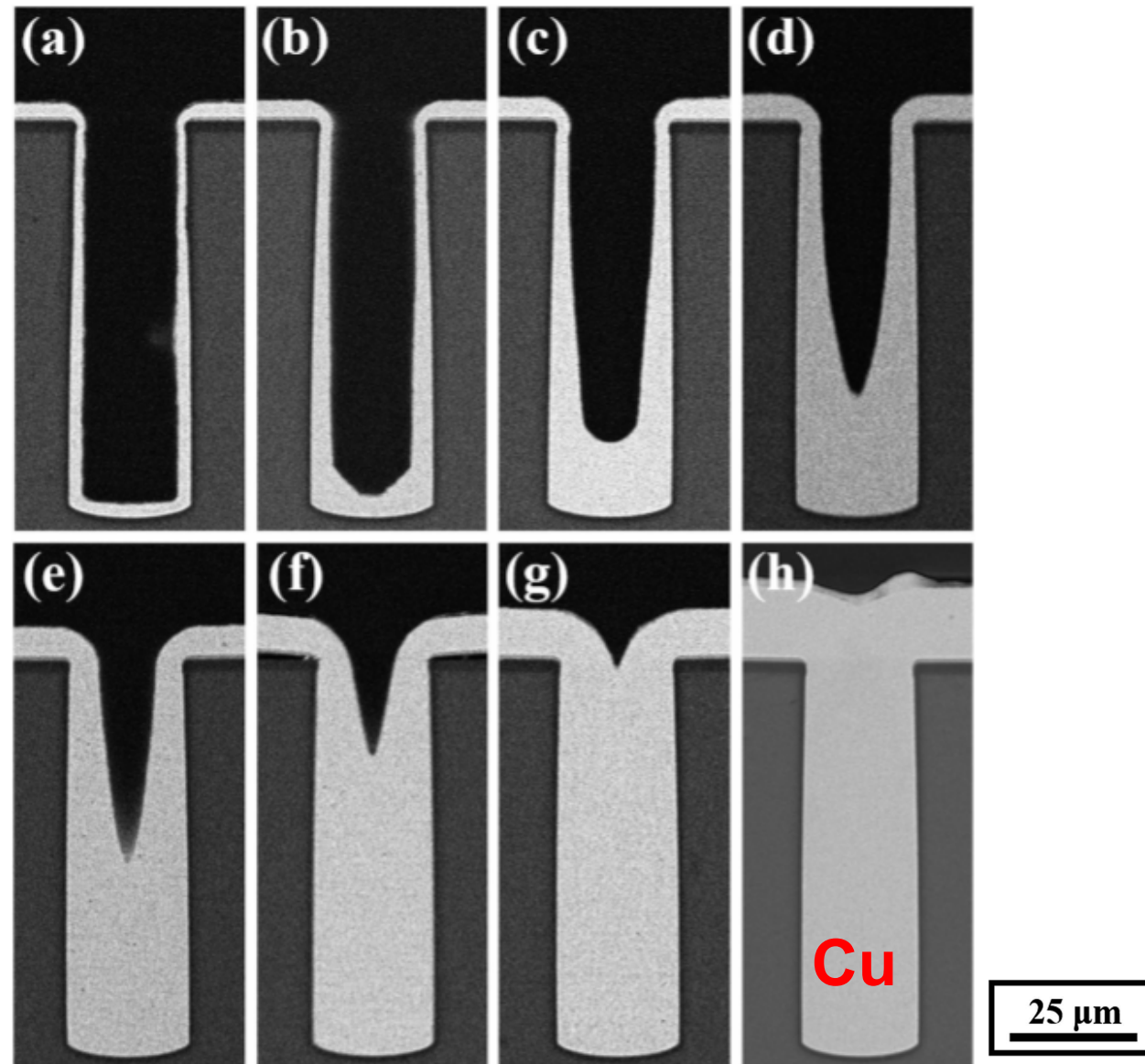
Copper Electroplating (电镀)

Printed Circuit Board

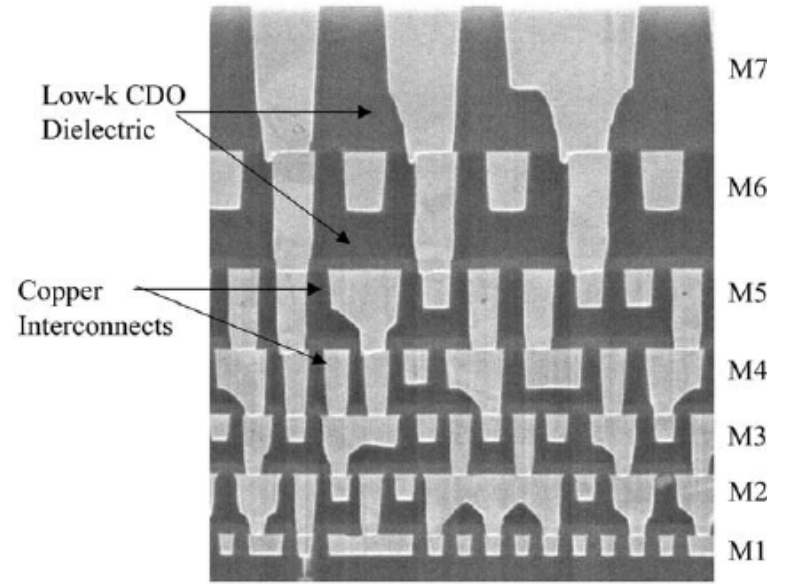
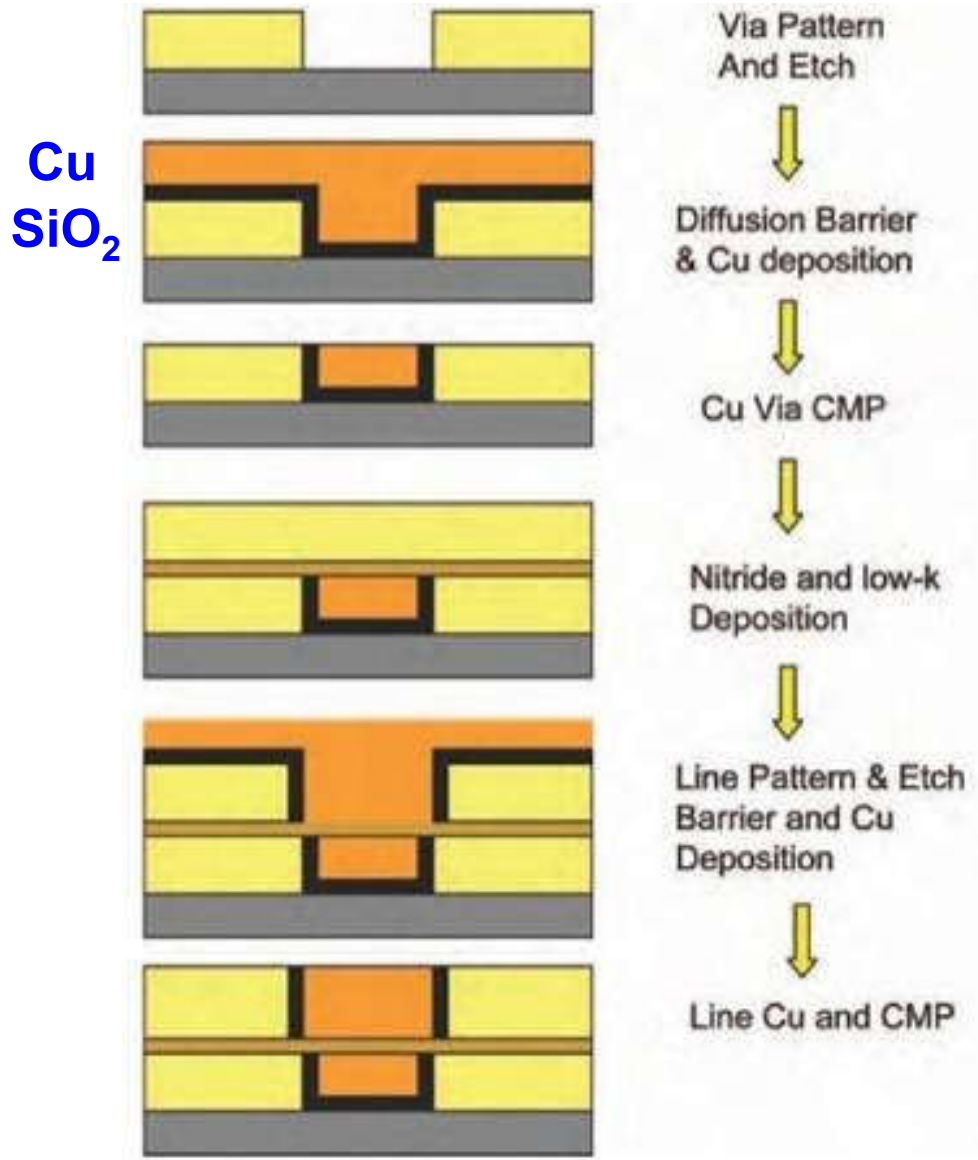


[Video](#)

Copper Electroplating (电镀)



Damascene Process for Cu

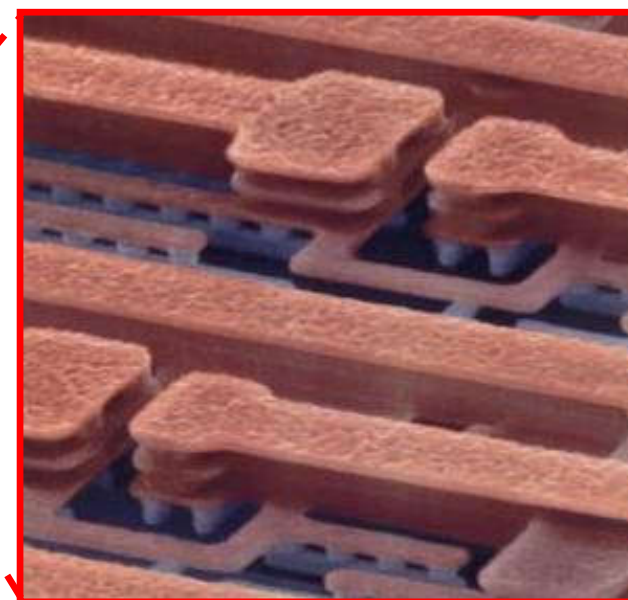
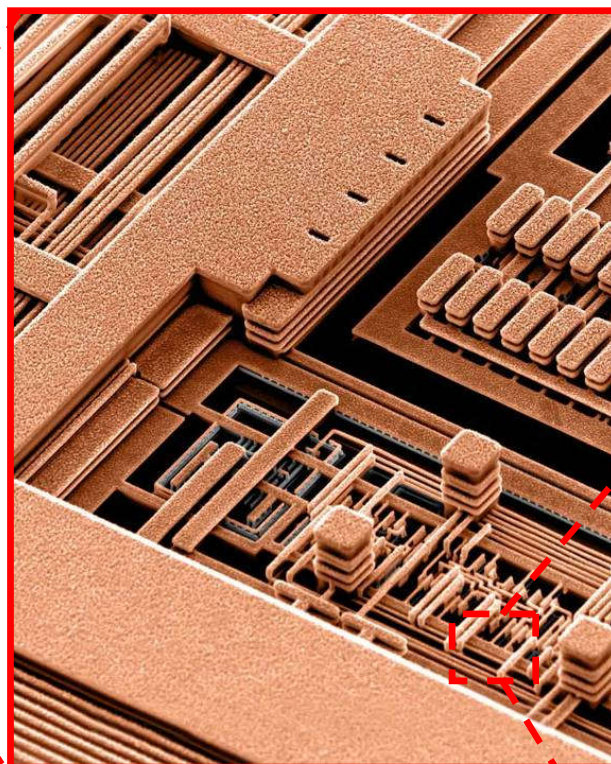


ancient art work

Damascene Process for Cu

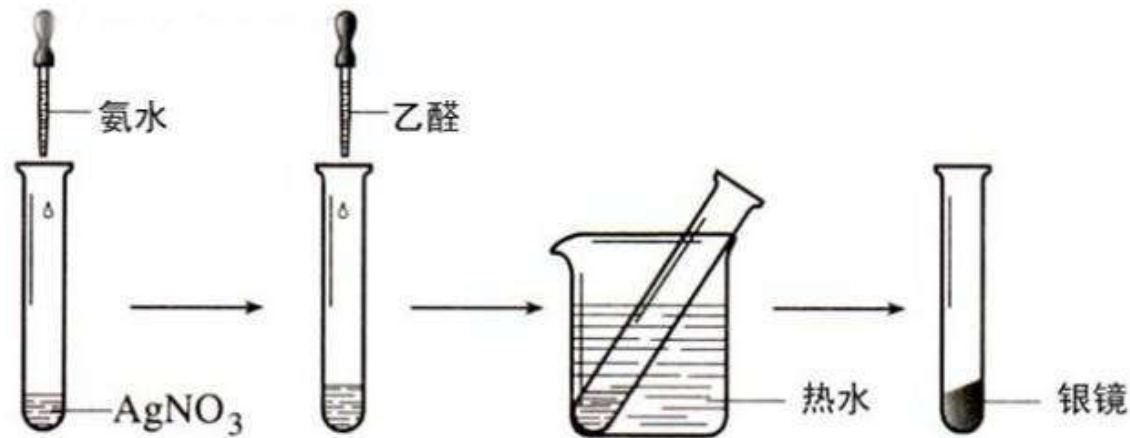


Electroplating + CMP
dirtiest process for the most advanced IC

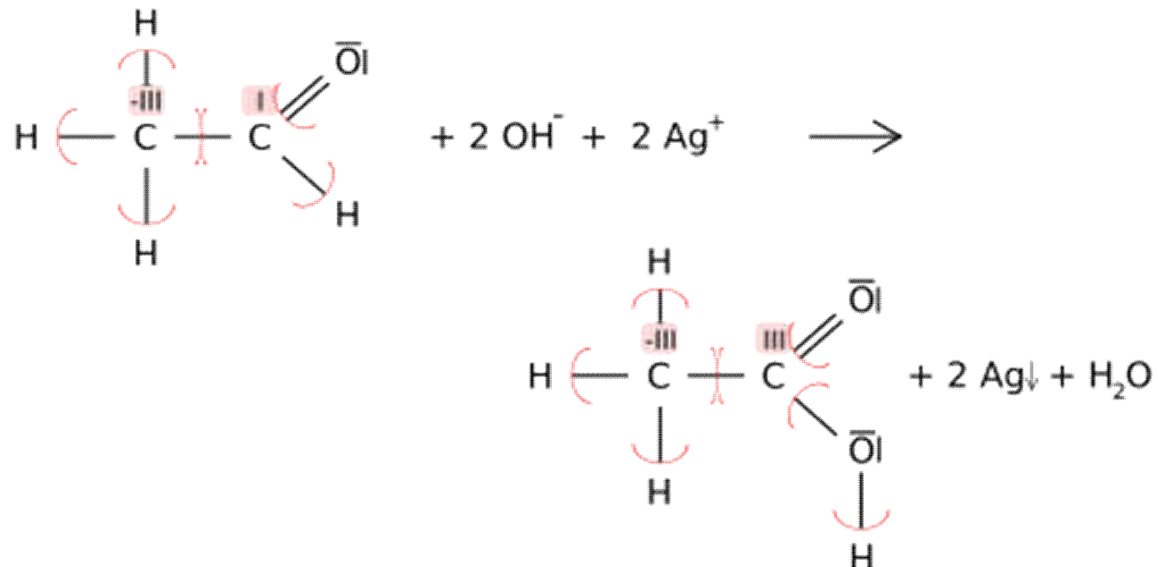


Electroless Plating

silver mirror reaction

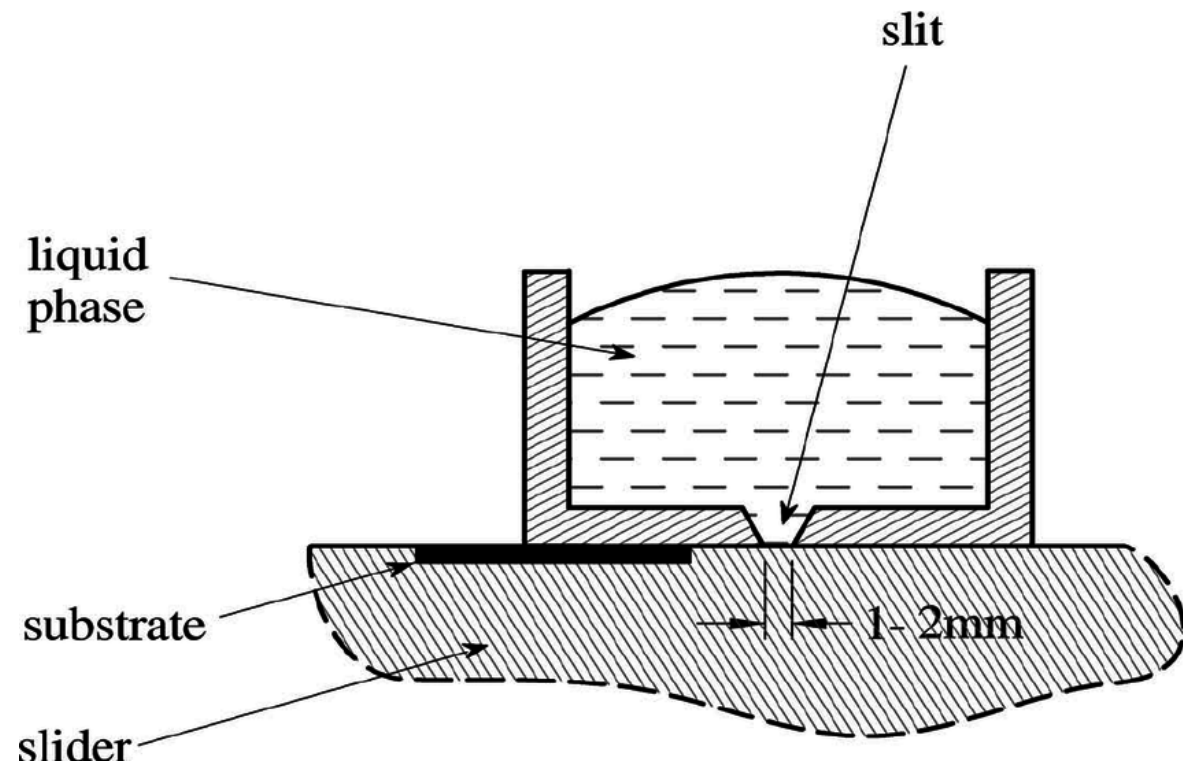
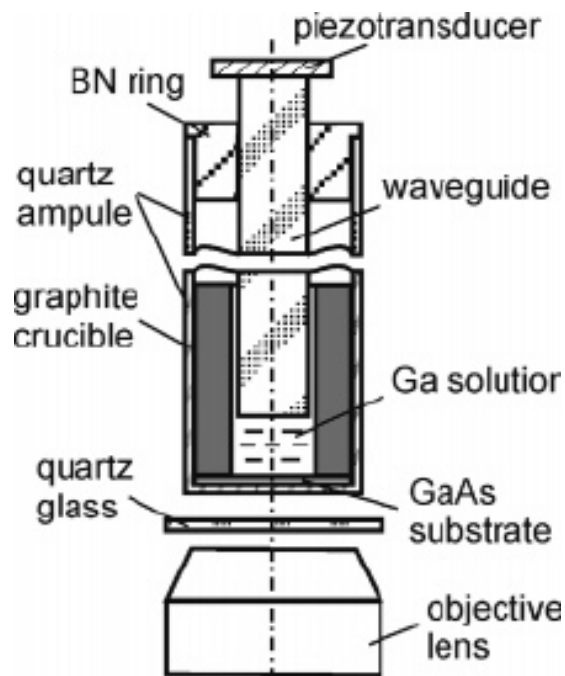


乙醛的银镜反应

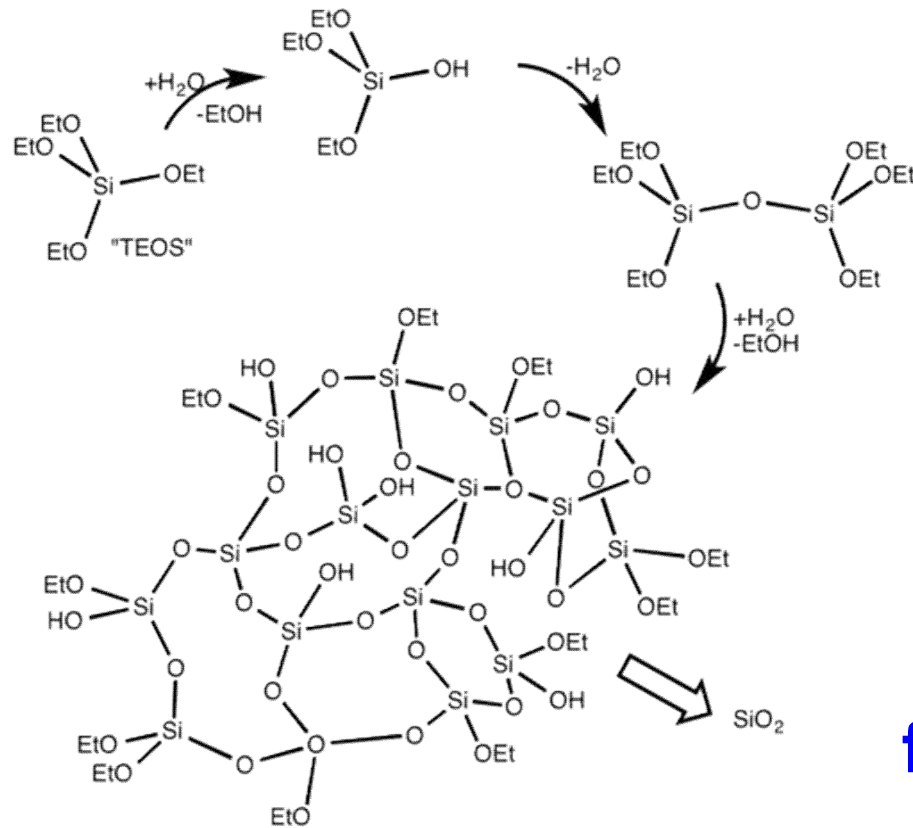


LPE - Liquid Phase Epitaxy

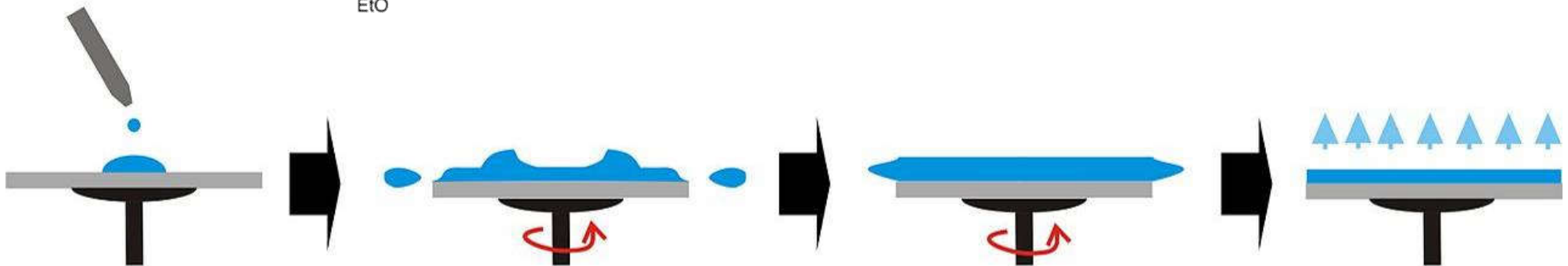
- Liquid Phase Epitaxy (LPE)
 - $2\text{Ga (l)} + 2\text{AsCl}_3 \text{ (l)} = 2\text{GaAs (s)} + 3\text{Cl}_2 \text{ (g)}$



Spin-on Glass (SOG)

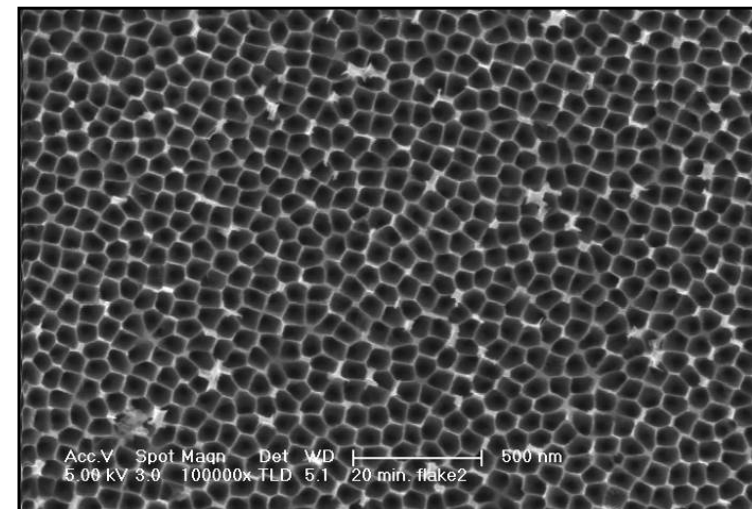
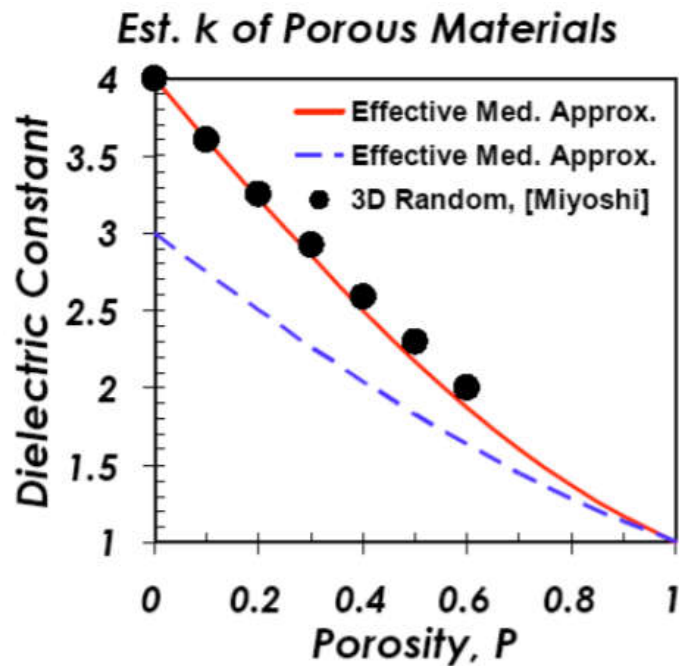
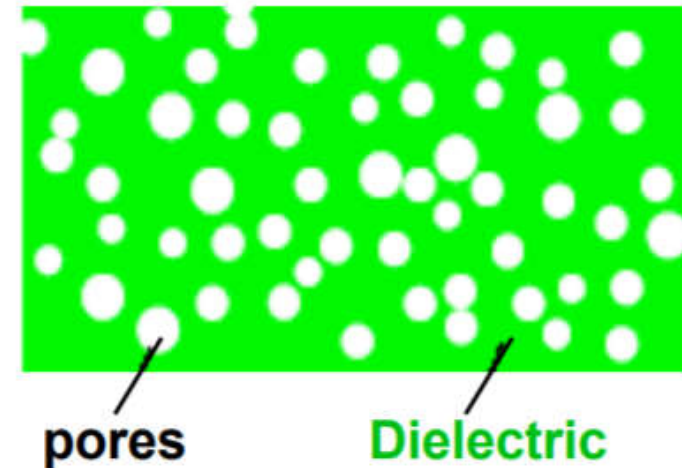


form SiO_2 from solvent



Porous SiO₂ for Low κ Dielectric

SiO ₂	$\kappa = 3.9$
air	$\kappa = 1.0$



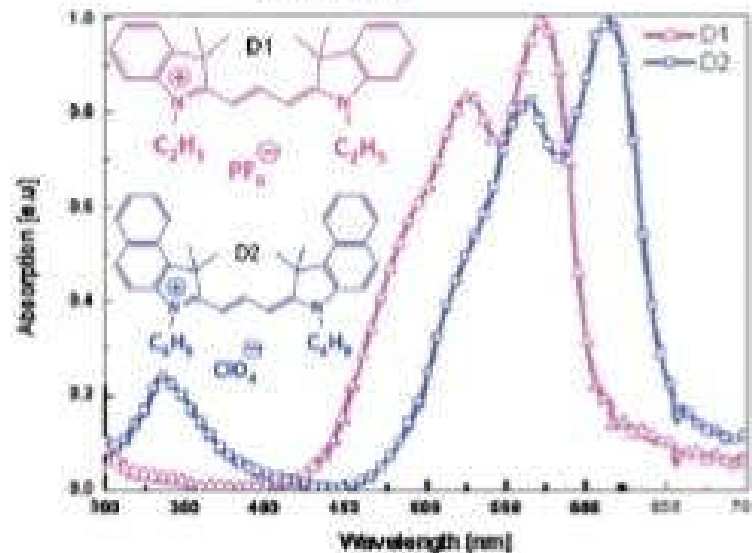
prepared by spin-on methods

Organic Solar Cells

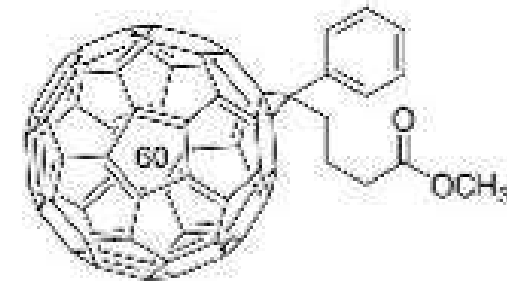
Solar Cell

Ag (70 nm)
MoO ₃ (30 nm)
Dye (30 nm)
PCBM (45 nm)
ZnO (30 nm)
ITO/Glass

9 mm²

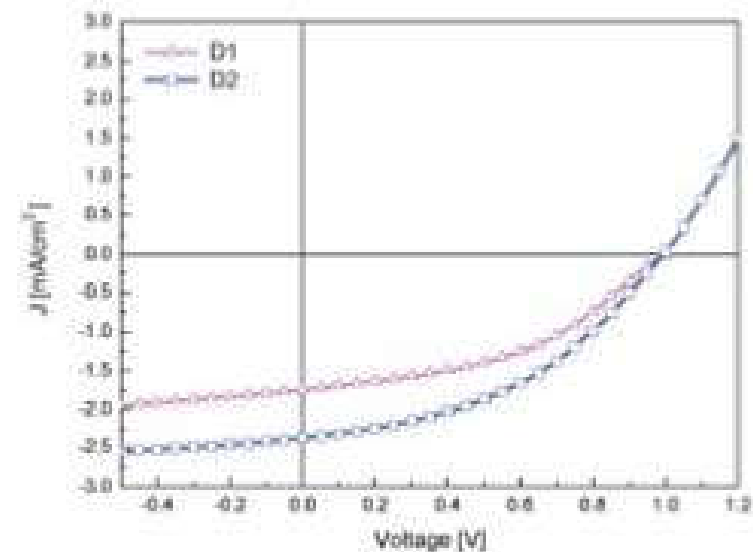


PCMB

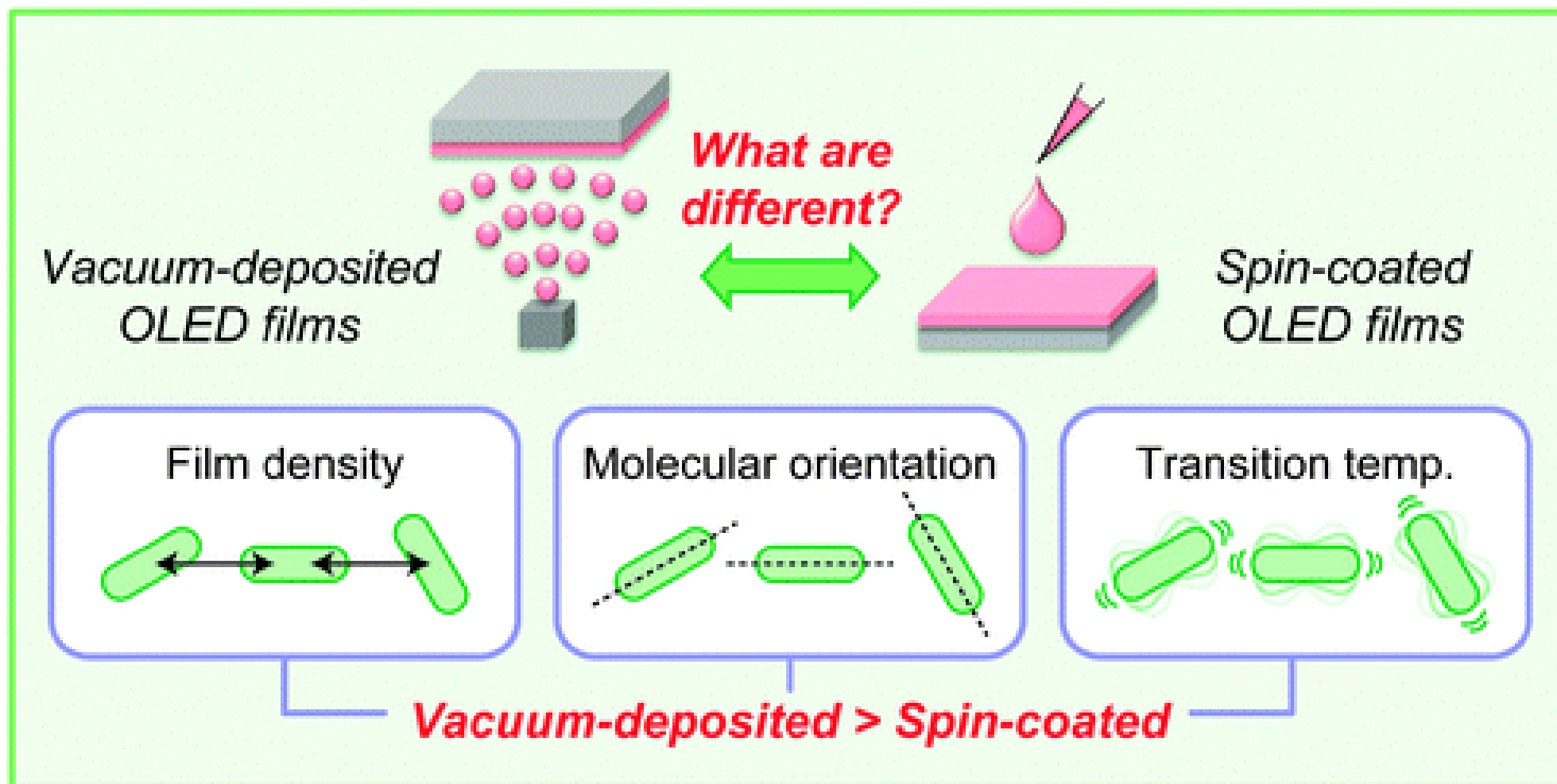


Doctor Blade
Spin coating

CSD: Spin coating ZnAc/ZnCOOH 400°C



OLEDs

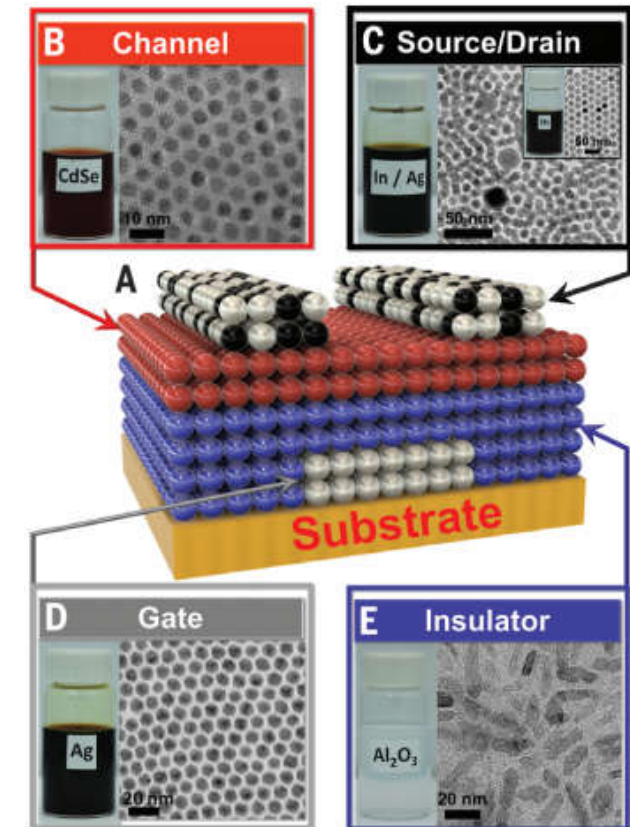
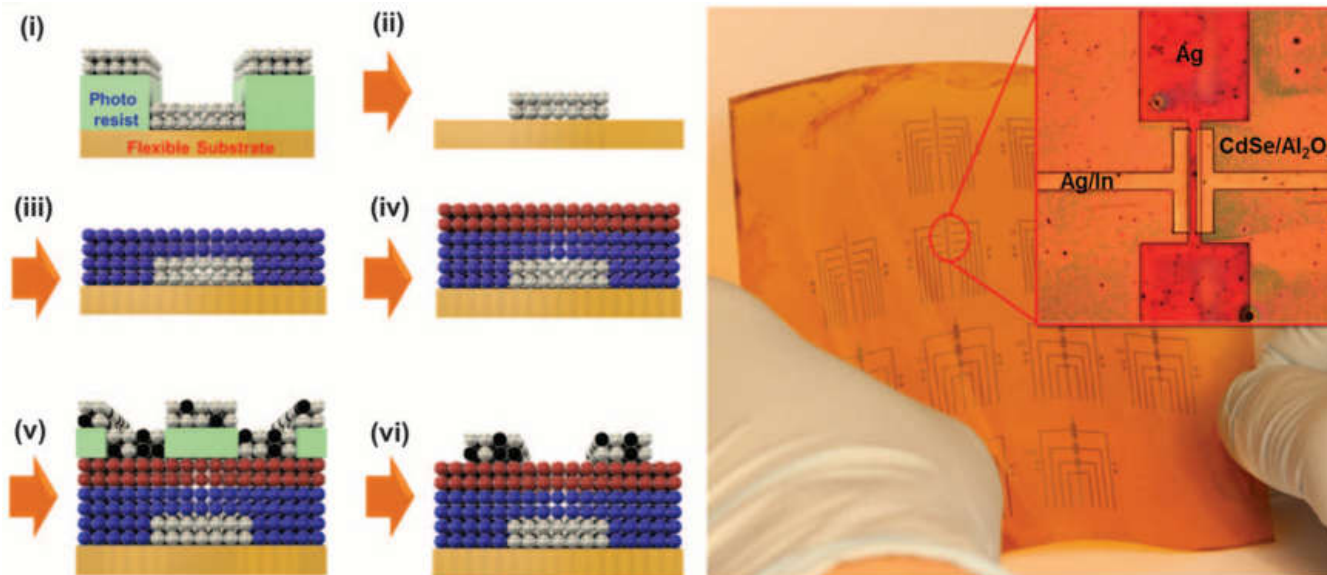


Fully Solution Processed Devices

ELECTRONICS

Exploiting the colloidal nanocrystal library to construct electronic devices

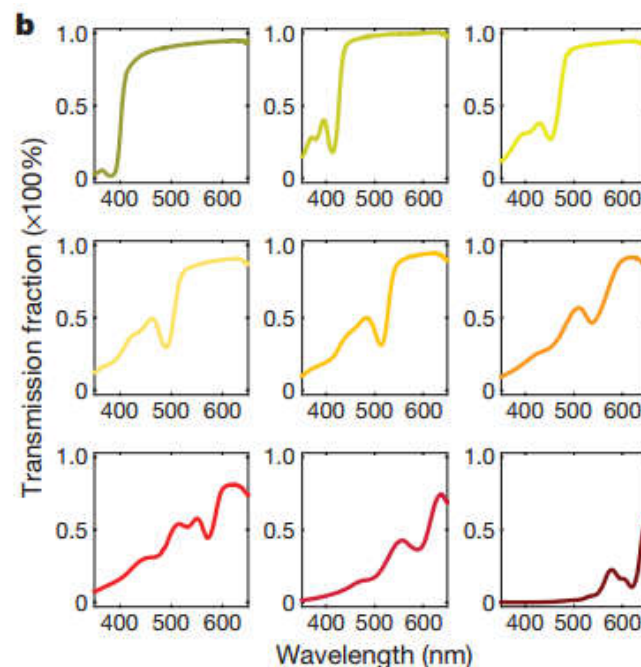
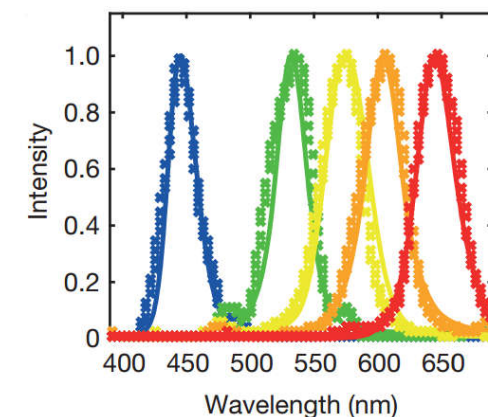
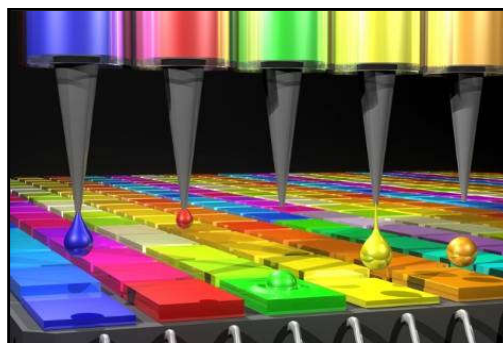
Ji-Hyuk Choi,^{1,2,3} Han Wang,⁴ Soong Ju Oh,^{1,5} Taejong Paik,¹ Pil Sung Jo,^{1,2} Jinwoo Sung,⁶ Xingchen Ye,⁷ Tianshuo Zhao,¹ Benjamin T. Diroll,⁷ Christopher B. Murray,^{1,7} Cherie R. Kagan^{1,4,7*}



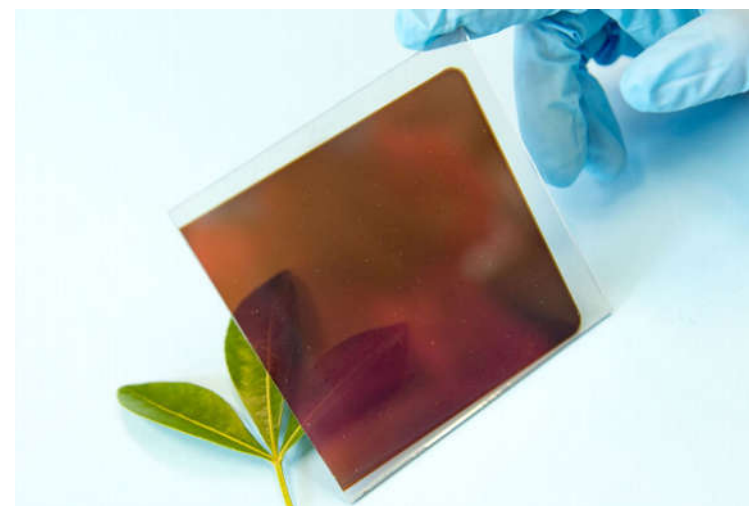
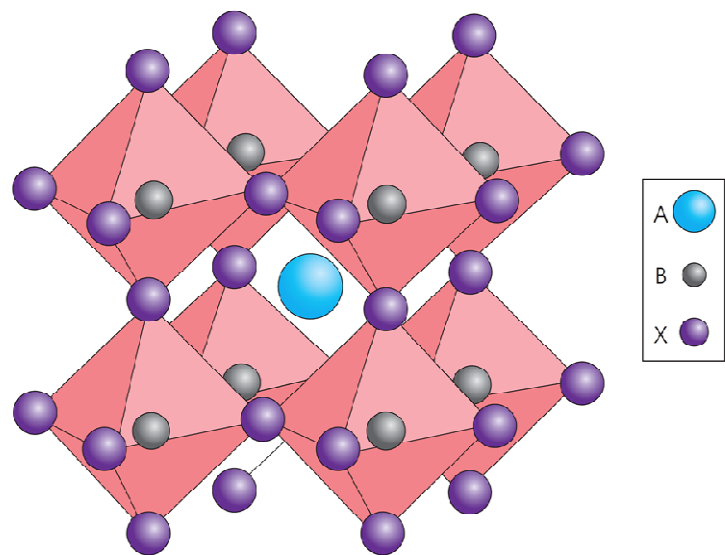
Colloidal Quantum Dots

A colloidal quantum dot spectrometer

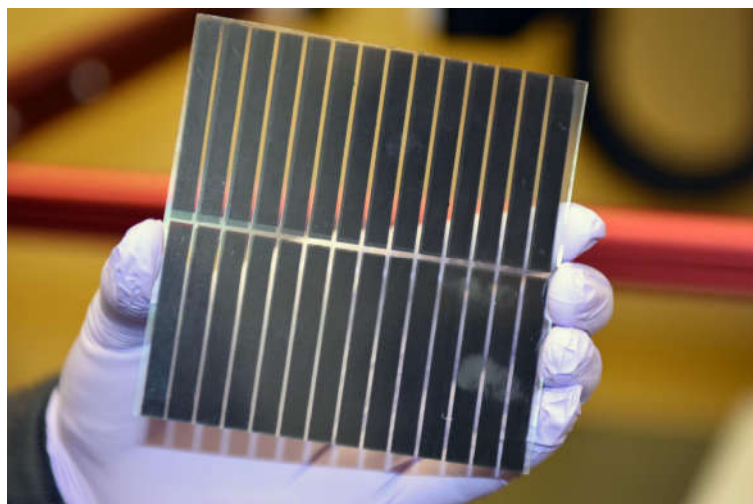
Jie Bao^{1,2,3} & Mounqi G. Bawendi²



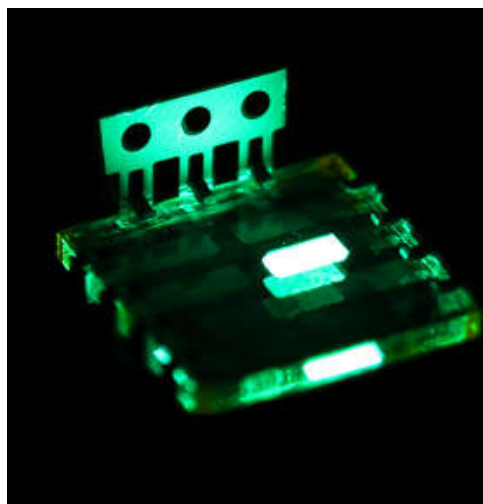
Perovskites (钙钛矿)



deposit by spin coating or evaporation



solar cells



LEDs

> 20 Nature/Science papers every year